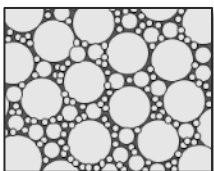


L□E□ Series

Original Material



High density
packing
Low loss
iron-based
magnetic material

Point

Reduce DCR

about **– 51%**

Low Core Loss

about **– 30%**

Process Features

“Unique Molding
Technology”
+
**High-performance
magnetic metal resin**

Applications

Smartphones/Automotive
Industrial Equipment/
Memory/PCs

High Current

about **x 1.7**

※ Comparison with metal products of the same size and inductance

·LSANB2520KKT2R2M (MA) Case Size(mm):2.5x2.0x1.0 Inductance:2.2uH Isat(max):1.5A Rdc(max):0.156Ω

·LSEUC2520KKT2R2M (ME) Case Size(mm):2.5x2.0x1.0 Inductance:2.2uH Isat(max):2.5A Rdc(max):0.076Ω

※MCOIL is a registered trademark or trademark of TAIYO YUDEN CO., LTD. in Japan and other countries.
The names of series noted in the text are excerpted from part numbers that indicate the types and characteristics of the products, and therefore are neither product names nor trademarks.